

## RX Family

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### USB Host Mass Storage Class Driver for USB Mini Firmware Using Firmware Integration Technology

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#### Introduction

This application note describes USB Host Mass Storage Class Driver(HMSC), which utilizes Firmware Integration Technology (FIT). This module operates in combination with the USB Basic Mini Host and Peripheral Driver. It is referred to below as the USB HMSC FIT module.

#### Target Device

RX111 Group  
RX113 Group  
RX231 Group  
RX23W Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate

#### Related Documents

1. Universal Serial Bus Revision 2.0 specification
2. USB Mass Storage Class Specification Overview Revision 1.1
3. USB Mass Storage Class Bulk-Only Transport Revision 1.0  
<http://www.usb.org/developers/docs/>
4. RX111 Group User's Manual: Hardware (Document number .R01UH0365)
5. RX113 Group User's Manual: Hardware (Document number.R01UH0448)
6. RX231 Group User's Manual: Hardware (Document number .R01UH0496)
7. RX23W Group User's Manual: Hardware (Document number .R01UH0823)
8. RX Family M3S-TFAT-Tiny: FAT file system software (Document number: R20AN0038EJ)
9. RX Family M3S-TFAT-Tiny: Memory Driver Interface Module (Document number: R20AN0335EJ)
10. USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note (Document number.R01AN2166)

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## 1. Overview

The USB HMSC FIT module, when used in combination with the USB-BASIC-F/W FIT module, operates as a USB host mass storage class driver (HMSC).

The HMSC comprises a USB mass storage class bulk-only transport (BOT) protocol. When combined with a file system and storage device driver, it enables communication with a BOT-compatible USB storage device.

Note that please use the M3S-TFAT-Tiny (Document number: R20AN0038) and Memory driver interface module (Document number: R20AN0335) in combination when using this driver.

This module supports the following functions.

1. Checking of connected USB storage devices (to determine whether or not operation is supported).
2. Storage command communication using the BOT protocol.
3. Support for SFF-8070i (ATAPI) USB mass storage subclass.

### 1.1 Please be sure to read

Please refer to the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note* when creating an application program using this driver.

This document is located in the "**reference\_documents**" folder within this package.

### 1.2 Note

This driver is not guaranteed to provide USB communication operation. The customer should verify operation when utilizing it in a system and confirm the ability to connect to a variety of different types of devices.

### 1.3 Limitation

1. Some MSC devices may be unable to be connected (because they are not recognized as storage devices).
2. MSC devices that return values of 1 or higher in response to the GetMaxLun command (mass storage class command) are not supported.
3. USB storage devices with a sector size of 512 bytes can be connected.
4. A device that does not respond to the READ\_CAPACITY command operates as a device with a sector size of 512 bytes.

### 1.4 Terms and Abbreviations

APL	: Application program
BOT	: Mass storage class Bulk Only Transport
FSL	: FAT File System Library
HCD	: Host Control Driver of
HDCCD	: Host Device Class Driver (device driver and USB class driver)
MGR	: Peripheral device state manager of HCD
MSC	: Mass Storage Class
RSK	: Renesas Starter Kits
TFAT	: Tiny FAT file system software for microcontrollers (M3S-TFAT-Tiny-RX)
USB-BASIC-FW	: USB Basic Mini Host and Peripheral Driver
USB	: Universal Serial Bus

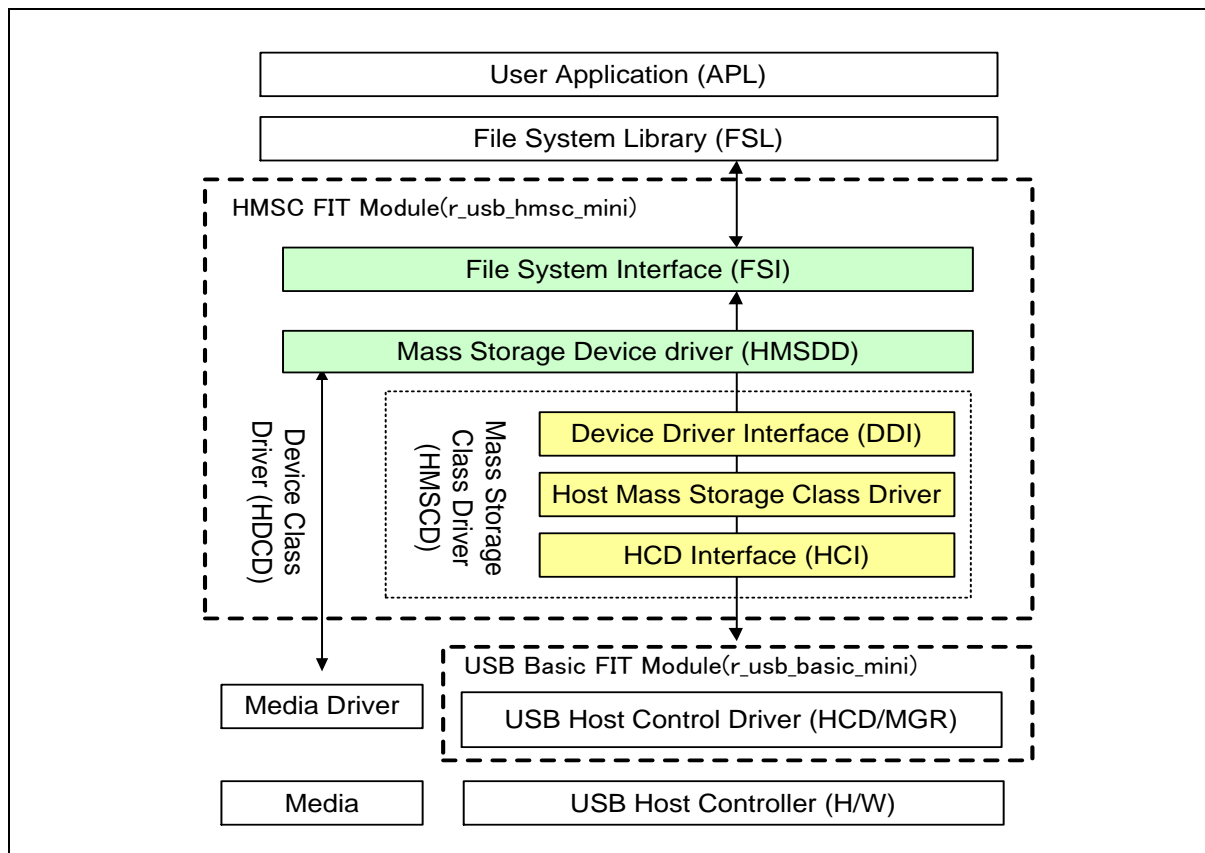
### 1.5 USB HMSC FIT Module

User needs to integrate this module to the project using `r_usb_basic_mini`. User can control USB H/W by using this module API after integrating to the project.

## 2. Software Configuration

HDCC (Host Device Class Driver) is the all-inclusive term for HMSDD (Host Mass Storage Device Driver) and HMSCD (USB Host Mass Storage Class Driver).

Figure 2-1 shows the HMSC software block diagram, with HDCC as the centerpiece. Table 2-1 describes each module.



**Figure 2-1 Software Module Structure**

**Table 2-1 Module**

Module	Description
FSI	FSL-HMSDD interface functions. They should be modified to match FSL.
HMSDD	To be created (modified) by the customer to match the storage media.
DDI	HMSDD-HMSCD interface functions. They should be modified to match the storage media interface of HMSDD.
HMSCD	The USB host mass storage class driver. It appends BOT protocol information to storage commands and sends requests to HCD. It also manages the BOT sequence. The storage commands should be added (modified) by the customer to match the system specifications. SFF-8070i (ATAPI) is supported in the example code.
HCI	HMSCD-HCD interface functions.
MGR	Enumerates the connected devices and starts HMSCD. Also performs device state management.
HCD	USB host hardware control driver.

### 3. API Information

This Driver API follows the Renesas API naming standards.

#### 3.1 Hardware Requirements

This driver requires your MCU support the following features:

- USB

#### 3.2 Software Requirements

This driver is dependent upon the following packages:

- r\_bsp
- r\_usb\_basic\_mini

#### 3.3 Operating Confirmation Environment

Table 3-1 shows the operating confirmation environment of this driver.

Table 3-1 Operation Confirmation Environment

Item	Contents
C compiler	Renesas Electronics C/C++ compiler for RX Family V.3.01.00 (The option "-lang=C99" is added to the default setting of IDE)
	GCC for Renesas RX 4.08.04.201902 (The option "-std=gnu99" is added to the default setting of IDE)
	IAR C/C++ Compiler for Renesas RX version 4.12.01
Endian	Little Endian, Big Endian
USB Driver Revision Number	Rev.1.12
Using Board	Renesas Starter Kit for RX111 Renesas Starter Kit for RX113 Renesas Starter Kit for RX231 Renesas Solution Starter Kit for RX23W

#### 3.4 Usage of Interrupt Vector

Table 3-2 shows the interrupt vector which this driver uses.

Table 3-2 List of Usage Interrupt Vectors

Device	Contents
RX111	USBIO Interrupt (Vector number: 36) / USBR0 Interrupt (Vector number: 90) USB D0FIFO0 Interrupt (Vector number: 36) / USB D1FIFO0 Interrupt (Vector number: 37)
RX113	
RX231	
RX23W	

#### 3.5 Header Files

All API calls and their supporting interface definitions are located in *r\_usb\_basic\_mini\_if.h* and *r\_usb\_hmsc\_mini\_if.h*.

### 3.6 Integer Types

This project uses ANSI C99 “Exact width integer types” in order to make the code clearer and more portable. These types are defined in *stdint.h*.

### 3.7 Compile Setting

For compile settings, refer to chapter 8, **Configuration (r\_usb\_hmssc\_mini\_config.h)** in this document and chapter "Configuration" in the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note*.

### 3.8 ROM / RAM Size

The follows show ROM/RAM size of this driver.

1. CC-RX (Optimization Level: Default)

	Checks arguments	Does not check arguments
ROM size	20.9K bytes (Note 4)	20.7K bytes (Note 5)
RAM size	6.0K bytes	6.0K bytes

2. GCC (Optimization Level: -O2)

	Checks arguments	Does not check arguments
ROM size	25.1K bytes (Note 4)	24.9K bytes (Note 5)
RAM size	5.9K bytes	5.9K bytes

3. IAR (Optimization Level: Medium)

	Checks arguments	Does not check arguments
ROM size	17.0K bytes (Note 4)	16.8K bytes (Note 5)
RAM size	4.5K bytes	4.5K bytes

[Note]

1. ROM/RAM size for BSP and USB Basic Driver is included in the above size.
2. ROM/RAM size for FAT is not included in the above size.
3. The above is the size when specifying RX V2 core option.
4. The ROM size of “Checks arguments” is the value when *USB\_CFG\_ENABLE* is specified to *USB\_CFG\_PARAM\_CHECKING* definition in *r\_usb\_basic\_mini\_config.h* file.
5. The ROM size of “Does not check arguments” is the value when *USB\_CFG\_DISABLE* is specified to *USB\_CFG\_PARAM\_CHECKING* definition in *r\_usb\_basic\_mini\_config.h* file.

### 3.9 Argument

For the structure used in the argument of API function, refer to chapter "**Structures**" in the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note*.

### 3.10 Adding the FIT Module to Your Project

This module must be added to each project in which it is used. Renesas recommends the method using the Smart Configurator described in (1) or (3) below. However, the Smart Configurator only supports some RX devices. Please use the methods of (2) or (4) for RX devices that are not supported by the Smart Configurator.

- (1) Adding the FIT module to your project using “Smart Configurator” on e<sup>2</sup> studio

By using the Smart Configurator in e<sup>2</sup> studio, the FIT module is automatically added to your project. Refer to “Renesas e<sup>2</sup> studio Smart Configurator User Guide (R20AN0451)” for details.

- (2) Adding the FIT module to your project using the FIT Configurator in e<sup>2</sup> studio

By using the FIT Configurator in e<sup>2</sup> studio, the FIT module is automatically added to your project. Refer to “Adding Firmware Integration Technology Modules to Projects (R01AN1723)” for details.

- (3) Adding the FIT module to your project using the Smart Configurator in CS+

By using the Smart Configurator Standalone version in CS+, the FIT module is automatically added to your project. Refer to “Renesas e<sup>2</sup> studio Smart Configurator User Guide (R20AN0451)” for details.

- (4) Adding the FIT module to your project on CS+

In CS+, please manually add the FIT module to your project. Refer to “Adding Firmware Integration Technology Modules to CS+ Projects (R01AN1826)” for details.

#### 4. Target Peripheral List (TPL)

For the structure used in the argument of API function, refer to chapter " **How to Set the Target Peripheral List (TPL)**" in the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note*.



## 5. Class Driver

### 5.1 Class Request

This driver supports the following class request.

**Table 5-1 Class Request**

Request	Description
GetMaxLun	Gets the maximum number of units that are supported.
MassStorageReset	Cancels a protocol error.

### 5.2 Storage Command

This driver supports the following storage command.

1. TEST\_UNIT\_READY
2. REQUEST\_SENSE
3. MODE\_SELECT10
4. MODE\_SENSE10
5. PREVENT\_ALLOW
6. READ\_FORMAT\_CAPACITY
7. READ10
8. WRITE10

## 6. API Functions

The following are Host Mass Storage Class specific API functions

API	Description
R_USB_HmscStrgCmd()	Issues a Mass Storage command.

**Note:**

1. Uses the FAT (File Allocation Table) API to access storage media.
2. Refer to chapter "API" in the document(Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note* when using other API.

## 6.1 R\_USB\_HmscStrgCmd

### Issues a Mass Storage command

#### Format

usb\_err\_t R\_USB\_HmscStrgCmd(uint8\_t \*p\_buf, uint16\_t command)

#### Arguments

p\_buf Pointer to data area  
command Mass storage command

#### Return Value

USB\_SUCCESS Successfully completed  
USB\_ERR\_PARA Parameter error  
USB\_ERR\_NG Other error

#### Description

The Mass Storage command assigned to the argument (*command*) is issued to the MSC device. An application program can check the completion of the Mass Storage command with the *USB\_STS\_MSC\_CMD\_COMPLETE* return value of the *R\_USB\_GetEvent* function.

If a Mass Storage command with response data is issued, after checking *USB\_STS\_MSC\_CMD\_COMPLETE* return value of the *R\_USB\_GetEvent* function, an application program can obtain the response data from the area indicated by the second argument (*p\_buf*). Check the member (*size*) of the *usb\_ctrl\_t* structure to get the size of the response data that was received.

Assign the following to the argument (*command*).

**Table 6-1 Mass Storage Command**

MassStorage Command
USB_ATAPI_TEST_UNIT_READY
USB_ATAPI_REQUEST_SENSE
USB_ATAPI_INQUIRY
USB_ATAPI_MODE_SELECT10
USB_ATAPI_PREVENT_ALLOW
USB_ATAPI_READ_FORMAT_CAPACITY
USB_ATAPI_READ_CAPACITY
USB_ATAPI_MODE_SENSE10

#### Note

- Do not assign a pointer to the auto variable (stack) area to the arguments (*p\_buf*).
- Assign *USB\_NULL* to the argument (*p\_buf*) when issuing the mass storage command without the response data.
- If a command other than the Mass Storage commands listed in Table 6-1 is assigned to the argument (*command*), then *USB\_ERR\_PARA* will be the return value.
- When calling FAT API and this API after issuing the Mass storage command by this API, be sure to call these APIs after checking the return value (*USB\_STS\_CMD\_COMPLETE*) of *R\_USB\_GetEvent* function.
- Refer to chapter "7. Return Value (USB\_STS\_MSC\_CMD\_COMPLETED) of R\_USB\_GetEvent Function" about CSW.
- The CSW information is set to the member (*status*) of the *usb\_ctrl\_t* structure. If the value of the member (*status*) is *USB\_CSW\_FAIL*, issue the "Requeset Sense" command to the MSC device using this API.
- Set the page code (1 Byte) of the "Mode Sense10" command in the start address to the area indicated by the 2nd argument (*p\_buf*).

8. Set the parameter data for the "*Mode Select10*" command to the area indicated by the 2nd argument (*p\_buf*) based on the specification for USB Mass Storage Subclass (SFF-8070i etc).
9. This function can be called when the USB device is in the configured state. When the API is called in any other state, *USB\_ERR\_NG* is returned.

**Example**

```
void usb_application( void )
{
    usb_ctrl_t ctrl;
    usb_err_t err;
    :
    while (1)
    {
        switch (R_USB_GetEvent(&ctrl))
        {
            :
            case USB_STS_CONFIGURED:
                :
                g_buf[0] = 0x3F;    /* Page Code */
                R_USB_HmscStrgCmd( &g_buf, USB_ATAPI_MODE_SENSE10 );
                :
                break;
            case USB_STS_MSC_CMD_COMPLETE:
                if( ctrl.status == USB_CSW_FAIL )
                {
                    R_USB_HmscStrgCmd(&ctrl, &g_buf, USB_ATAPI_REQUEST_SENSE);
                }
                :
                break;
            :
        }
    }
}
```

## 7. Return Value (USB\_STS\_MSC\_CMD\_COMPLETED) of R\_USB\_GetEvent Function

After the completion of a Mass Storage command is checked with the *R\_USB\_HmscStrgCmd* function, if the *R\_USB\_GetEvent* function is called, then *USB\_STS\_MSC\_CMD\_COMPLETE* will be the return value. In addition, the following members of the *usb\_ctrl\_t* structure also have information:

size : Size of response data  
status : CSW information

### Note:

1. The member (*size*) has the size of the response data sent from MSC device.
2. The member (*status*) has bCSWStatus of the CSW (Command Status Wrapper):

USB_CSW_SUCCESS	(Value: 00H)	: Successful
USB_CSW_FAIL	(Value: 01H)	: Failed
USB_CSW_PHASE	(Value: 02H)	: Phase error

## 8. Configuration (r\_usb\_hmsc\_mini\_config.h)

Please set the following according to your system.

### Note:

Be sure to set *r\_usb\_basic\_mini\_config.h* file as well. For *r\_usb\_basic\_mini\_config.h* file, refer to chapter "**Configuration**" in the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note*.

### 1. Setting pipe to be used

Set the pipe number (PIPE1 to PIPE5) to use for Bulk IN/OUT transfer. Do not set the same pipe number for the definitions of *USB\_CFG\_HMSC\_BULK\_IN* and *USB\_CFG\_HMSC\_BULK\_OUT*.

#define	USB_CFG_HMSC_BULK_IN	Pipe number (USB_PIPE1 to USB_PIPE5)
#define	USB_CFG_HMSC_BULK_OUT	Pipe number (USB_PIPE1 to USB_PIPE5)

## 9. Creating an Application

Refer to the chapter “**Creating an Application Program**” in the document (Document number: R01AN2166) for *USB Basic Mini Host and Peripheral Driver (USB Mini Firmware) using Firmware Integration Technology Application Note*.

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## Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Dec 1, 2014	—	First edition issued.
1.01	Jun 1, 2015	—	RX231 is added in the target device.
1.02	Dec 28, 2015	—	Upgrading of this USB driver by upgrading of "USB Basic Mini Firmware (R01AN2166)".
1.10	Nov 30, 2018	—	<ol style="list-style-type: none"> <li>1. Supporting Smart Configurator.</li> <li>2. The following chapter is added. <ol style="list-style-type: none"> <li>(1). 5. Class Driver</li> <li>(2). 6. API Functions</li> <li>(3). 7. Return Value (USB_STS_MSC_CMD_COMPLETED) of R_USB_GetEvent Function</li> <li>(4). 8. Configuration (r_usb_hmsc_mini_config.h)</li> </ol> </li> <li>3. The following chapters are changed. <ol style="list-style-type: none"> <li>(1). 3. API Information</li> <li>(2). 9. Creating an Application</li> </ol> </li> <li>4. The following chapters are deleted.  " How to Register Class Driver", "System Resources", "Task ID and Priority Setting", "File System Interface", "Host Mass Storage Device Driver", "USB Mass Storage Class Driver" </li> </ol>
1.11	May 31, 2019	—	Support GCC compiler and IAR compiler.
1.12	Jun 30, 2019	—	RX23W is added in the target device.

## General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

### 1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.  
In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.  
In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

### 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

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Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

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